PRELIMINARY

Notice: This is not a final specification.
Some parametric limits are subject to change.

MITSUBISHI MICROCOMPUTERS

M37736M4BXXXGP

SINGLE-CHIP 16-BIT CMOS MICROCOMPUTER

DESCRIPTION

The M37736M4BXXXGP is a single-chip microcomputer using the 7700 Family core. This single-chip microcomputer has a CPU and a bus interface unit. The CPU is a 16-bit parallel processor that can be an 8-bit parallel processor, and the bus interface unit enhances the memory access efficiency to execute instructions fast. This microcomputer also includes a 32 kHz oscillation circuit, in addition to the ROM, RAM, multiple-function timers, serial I/O, A-D converter, and others.

In the M37736M4BXXXGP, as the multiplex method of the external bus, either of 2 types can be selected.

FEATURES

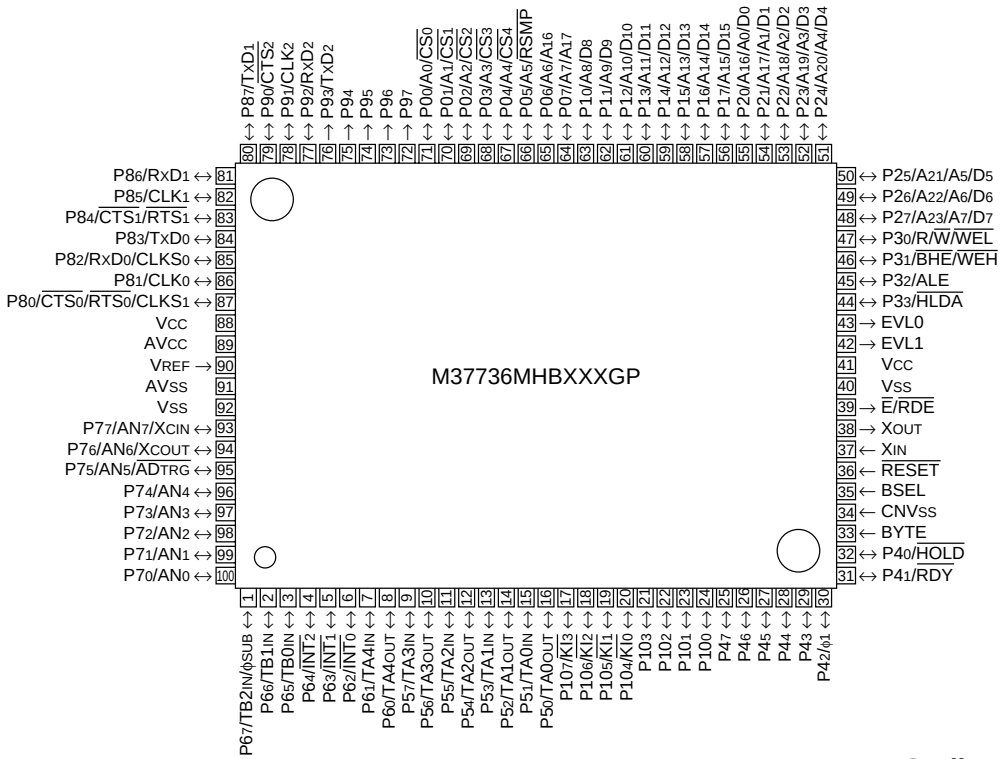
- Number of basic instructions 103
- Memory size ROM ..... 32 Kbytes
  RAM ..... 2048 bytes
- Instruction execution time
  The fastest instruction at 25 MHz frequency ..... 160 ns
- Single power supply ..... 5 V ± 10%
- Low power dissipation (at 25 MHz frequency)
  .....47.5 mW (Typ.)
- Interrupts ..... 19 types, 7 levels
- Multiple-function 16-bit timer ..... 5 + 3
- Serial I/O (UART or clock synchronous) 3
- 10-bit A-D converter ..... 8-channel inputs
- 12-bit watchdog timer
- Programmable input/output, output
  (ports P0, P1, P2, P3, P4, P5, P6, P7, P8, P9, P10).....84
- Clock generating circuit ..... 2 circuits built-in
- Package .....100-pin QFP

APPLICATION

Control devices for general commercial equipment such as office automation, office equipment, and others.

Control devices for general industrial equipment such as communication equipment, and others.

PIN CONFIGURATION (TOP VIEW)



Outline 100P6S-A

MITSUBISHI ELECTRIC

PRELIMINARY
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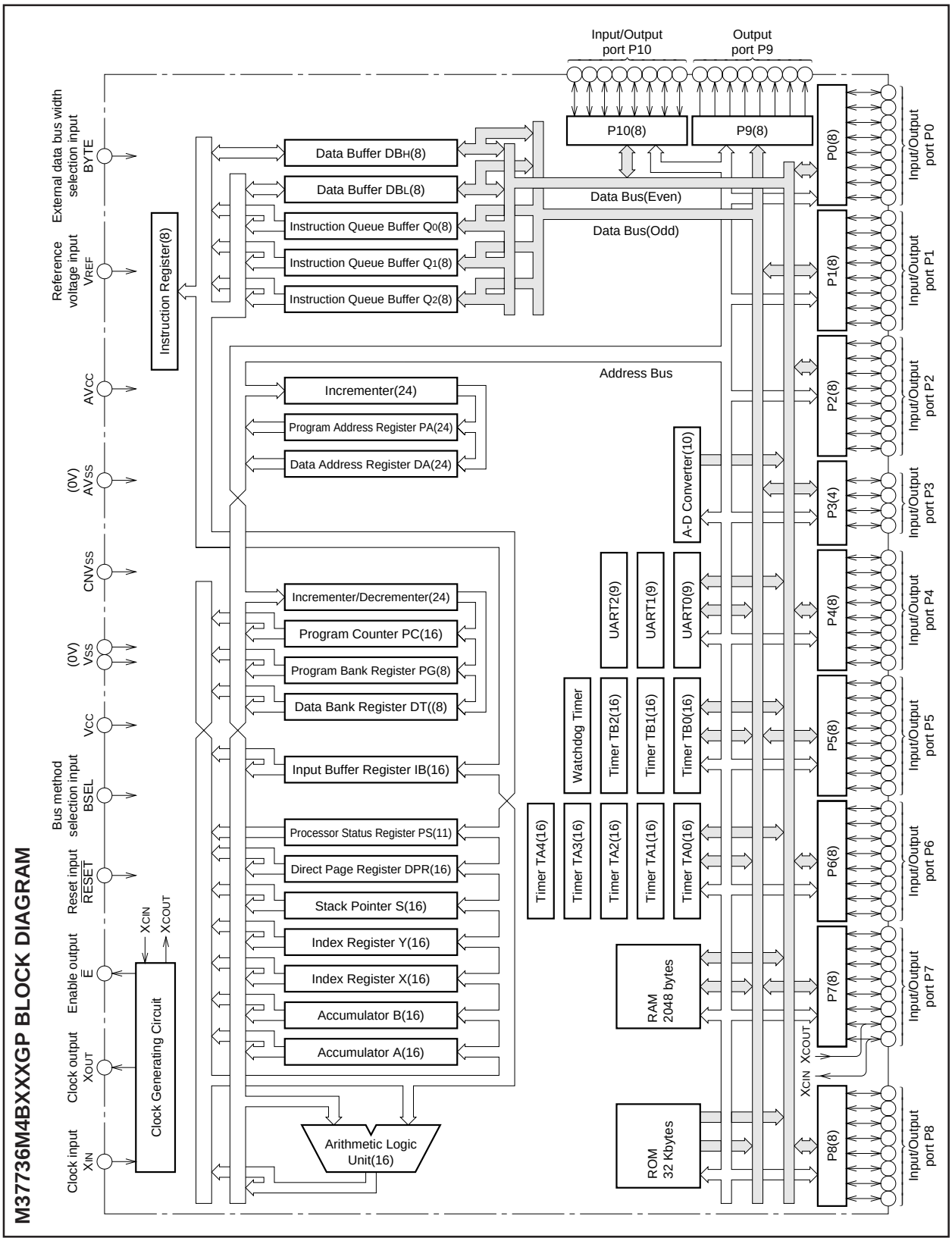
M37736M4BXXXGP BLOCK DIAGRAM



MITSUBISHI ELECTRIC

PRELIMINARY
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FUNCTIONS OF M37736M4BXXXGP

Parameter		Functions
Number of basic instructions		103
Instruction execution time		160 ns (the fastest instruction at external clock 25 MHz frequency)
Memory size	ROM	32 Kbytes
	RAM	2048 bytes
Input/Output ports	P0 – P2, P4 – P8, P10	8-bit × 9
	P3	4-bit × 1
Output port	P9	8-bit × 1
Multi-function timers	TA0, TA1, TA2, TA3, TA4	16-bit × 5
	TB0, TB1, TB2	16-bit × 3
Serial I/O		(UART or clock synchronous serial I/O) × 3
A-D converter		10-bit × 1 (8 channels)
Watchdog timer		12-bit × 1
Interrupts		3 external types, 16 internal types Each interrupt can be set to the priority level (0 – 7.)
Clock generating circuit		2 circuits built-in (externally connected to a ceramic resonator or a quartz-crystal oscillator)
Supply voltage		5 V ± 10%
Power dissipation		47.5 mW (at external clock 25 MHz frequency)
Input/Output characteristic	Input/Output voltage	5 V
	Output current	5 mA
Memory expansion		External bus mode A; maximum 16 Mbytes, External bus mode B; maximum 1 Mbytes
Operating temperature range		–20 to 85 °C
Device structure		CMOS high-performance silicon gate process
Package		100-pin plastic molded QFP (100P6S-A)

PIN DESCRIPTION

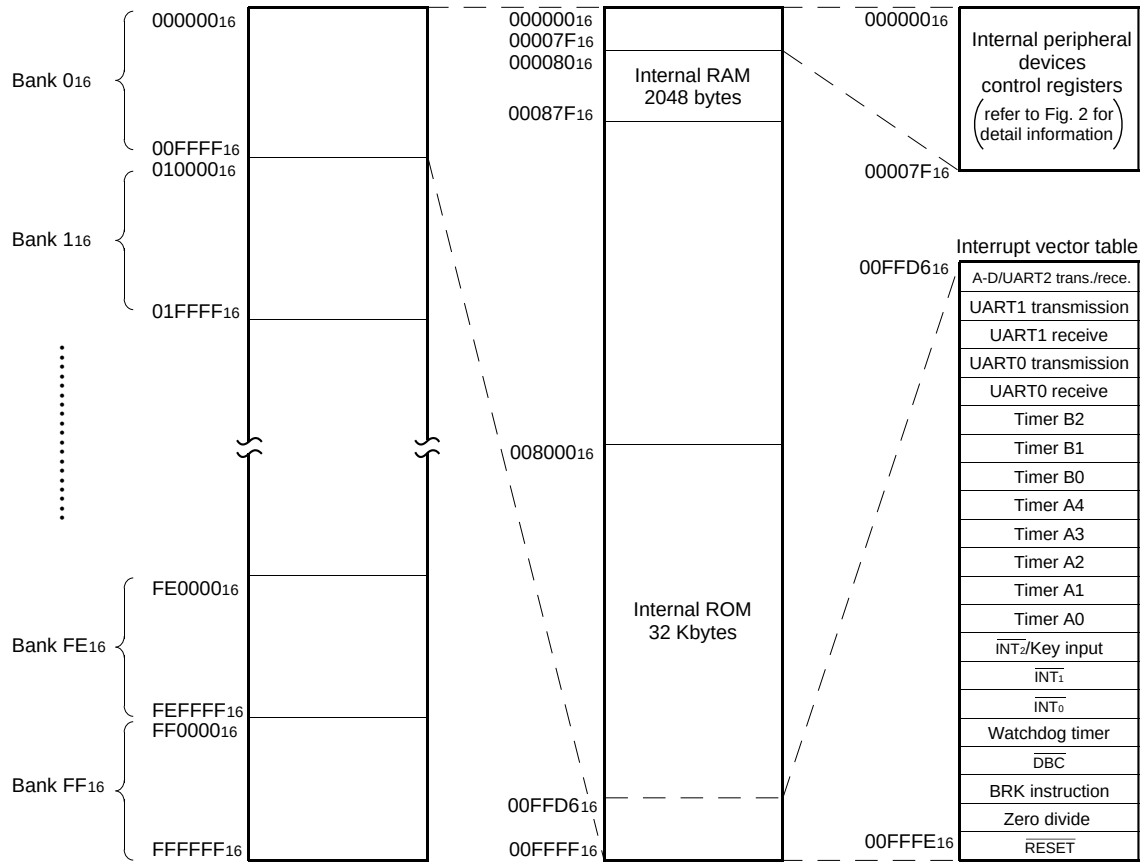
Pin	Name	Input/Output	Functions
Vcc, Vss	Power source		Apply 5 V ± 10% to Vcc and 0 V to Vss.
CNVss	CNVss input	Input	This pin controls the processor mode. Connect to Vss for the single-chip mode and the memory expansion mode, and to Vcc for the microprocessor mode.
$\overline{RESET}$	Reset input	Input	When "L" level is applied to this pin, the microcomputer enters the reset state.
X_{IN}	Clock input	Input	These are pins of main-clock generating circuit. Connect a ceramic resonator or a quartz-crystal oscillator between X_{IN} and X_{OUT}. When an external clock is used, the clock source should be connected to the X_{IN} pin, and the X_{OUT} pin should be left open.
X_{OUT}	Clock output	Output	
$\overline{E}$	Enable output	Output	This pin functions as the enable signal output pin which indicates the access status in the internal bus. In the external bus mode B and the memory expansion mode or the microprocessor mode, this pin output signal $\overline{RDE}$.
BYTE	External data bus width selection input	Input	In the memory expansion mode or the microprocessor mode, this pin determines whether the external data bus has an 8-bit width or a 16-bit width. The data bus has a 16-bit width when "L" signal is input and an 8-bit width when "H" signal is input.
BSEL	Bus method select input	Input	In the memory expansion mode or the microprocessor mode, this pin determines the external bus mode. The bus mode becomes the external bus mode A when "H" signal is input, and the external bus mode B when "L" signal is input.
AVcc, AVss	Analog power source input		Power source input pin for the A-D converter. Externally connect AVcc to Vcc and AVss to Vss.
V_{REF}	Reference voltage input	Input	This is reference voltage input pin for the A-D converter.
$P0_0$ – $P0_7$	I/O port P0	I/O	In the single-chip mode, port P0 becomes an 8-bit I/O port. An I/O direction register is available so that each pin can be programmed for input or output. These ports are in the input mode when reset. In the memory expansion mode or the microprocessor mode, these pins output address (A_0 – A_7) at the external bus mode A, and these pins output signals $\overline{CS_0}$ – $\overline{CS_4}$ and $\overline{RSMP}$, and addresses (A_{16}, A_{17}) at the external bus mode B.
$P1_0$ – $P1_7$	I/O port P1	I/O	In the single-chip mode, these pins have the same functions as port P0. When the BYTE pin is set to "L" in the memory expansion mode or the microprocessor mode and external data bus has a 16-bit width, high-order data (D_8 – D_{15}) is input/output or an address (A_8 – A_{15}) is output. When the BYTE pin is "H" and an external data bus has an 8-bit width, only address (A_8 – A_{15}) is output.
$P2_0$ – $P2_7$	I/O port P2	I/O	In the single-chip mode, these pins have the same functions as port P0. In the memory expansion mode or the microprocessor mode, low-order data (D_0 – D_7) is input/output or an address is output. When using the external bus mode A, the address is A_{16} – A_{23}. When using the external bus mode B, the address is A_0 – A_7.
$P3_0$ – $P3_3$	I/O port P3	I/O	In the single-chip mode, these pins have the same function as port P0. In the memory expansion mode or the microprocessor mode, R/$\overline{W}$, $\overline{BHE}$, ALE, and $\overline{HLDA}$ signals are output at the external bus mode A, and $\overline{WEL}$, $\overline{WEH}$, ALE, and $\overline{HLDA}$ signals are output at the external bus mode B.
$P4_0$ – $P4_7$	I/O port P4	I/O	In the single-chip mode, these pins have the same functions as port P0. In the memory expansion mode or the microprocessor mode, $P4_0$, $P4_1$ and $P4_2$ become $\overline{HOLD}$ and $\overline{RDY}$ input pins, and a clock ϕ_1 output pin, respectively. Functions of the other pins are the same as in the single-chip mode. However, in the memory expansion mode, $P4_2$ can be selected as an I/O port.
$P5_0$ – $P5_7$	I/O port P5	I/O	In addition to having the same functions as port P0 in the single-chip mode, these pins also function as I/O pins for timers A0 to A3.
$P6_0$ – $P6_7$	I/O port P6	I/O	In addition to having the same functions as port P0 in the single-chip mode, these pins also function as I/O pins for timer A4, input pins for external interrupt input ($\overline{INT_0}$ – $\overline{INT_2}$) and input pins for timers B0 to B2. $P6_7$ also functions as sub-clock ϕ_{SUB} output pin.
$P7_0$ – $P7_7$	I/O port P7	I/O	In addition to having the same functions as port P0 in the single-chip mode, these pins function as input pins for A-D converter. Additionally, $P7_6$ and $P7_7$ have the function as the output pin (X_{COUT}) and the input pin (X_{CIN}) of the sub-clock (32 kHz) oscillation circuit, respectively. When $P7_6$ and $P7_7$ are used as the X_{COUT} and X_{CIN} pins, connect a resonator or an oscillator between the both.
$P8_0$ – $P8_7$	I/O port P8	I/O	In addition to having the same functions as port P0 in the single-chip mode, these pins also function as I/O pins for UART 0 and UART 1.
$P9_0$ – $P9_7$	Output port P9	Output	Port P9 is an 8-bit I/O port. These ports are floating when reset. When writting to the port latch, these ports become the output mode. $P9_0$ – $P9_3$ also function as I/O port for UART 2.
$P10_0$ – $P10_7$	I/O port P10	I/O	In addition to having the same functions as port P0 in the single-chip mode, $P10_4$ – $P10_7$ also function as input pins for key input interrupt input ($\overline{KI_0}$ – $\overline{KI_3}$).
EVL0, EVL1	—	Output	These pins should be left open.

BASIC FUNCTION BLOCKS

The M37736M4BXXXGP has the same fuanctions as the M37736MHBXXXGP except for the memory allocation and the ROM area modification function.
Refer to the section on the M37736MHBXXXGP.

MEMORY

The memory map is shown in Figure 1. The address space has a capacity of 16 Mbytes and is allocated to addresses from 0_{16} to $FFFFFF_{16}$. The address space is divided by 64-Kbyte unit called bank. The banks are numbered from 0_{16} to FF_{16}.
However, banks 10_{16} – FF_{16} cannot be accessed in the external bus mode B.
Built-in ROM, RAM and control registers for internal peripheral devices are assigned to bank 0_{16}.
The 32-Kbyte area from addresses 8000_{16} to $FFFF_{16}$ is the built-in ROM. Addresses $FFD6_{16}$ to $FFFF_{16}$ are the RESET and interrupt vector addresses and contain the interrupt vectors. Refer to the section on interrupts for details.
The 2048-byte area allocated to addresses from 80_{16} to $87F_{16}$ is the built-in RAM. In addition to storing data, the RAM is used as stack during a subroutine call or interrupts.
Peripheral devices such as I/O ports, A-D converter, serial I/O, timer, and interrupt control registers are allocated to addresses from 0_{16} to $7F_{16}$.
Additionally, the internal ROM area can be modified by software. Refer to the section on ROM area modification function for details.
A 256-byte direct page area can be allocated anywhere in bank 0_{16} by using the direct page register (DPR). In the direct page addressing mode, the memory in the direct page area can be accessed with two words. Hence program steps can be reduced.



Notes 1. Internal ROM area can be modified. (Refer to the section on ROM area modification function.)
2. Banks 10_{16} – FF_{16} cannot be accessed in the external bus mode B.

Fig. 1 Memory map

Address (Hexadecimal notation)	
000000	
000001	
000002	Port P0 register
000003	Port P1 register
000004	Port P0 direction register
000005	Port P1 direction register
000006	Port P2 register
000007	Port P3 register
000008	Port P2 direction register
000009	Port P3 direction register
00000A	Port P4 register
00000B	Port P5 register
00000C	Port P4 direction register
00000D	Port P5 direction register
00000E	Port P6 register
00000F	Port P7 register
000010	Port P6 direction register
000011	Port P7 direction register
000012	Port P8 register
000013	Port P9 register
000014	Port P8 direction register
000015	
000016	Port P10 register
000017	
000018	Port P10 direction register
000019	
00001A	
00001B	
00001C	Reserved area (Note)
00001D	Reserved area (Note)
00001E	A-D control register 0
00001F	A-D control register 1
000020	A-D register 0
000021	
000022	A-D register 1
000023	
000024	A-D register 2
000025	
000026	A-D register 3
000027	
000028	A-D register 4
000029	
00002A	A-D register 5
00002B	
00002C	A-D register 6
00002D	
00002E	A-D register 7
00002F	
000030	UART 0 transmit/receive mode register
000031	UART 0 baud rate register (BRG0)
000032	UART 0 transmission buffer register
000033	
000034	UART 0 transmit/receive control register 0
000035	UART 0 transmit/receive control register 1
000036	UART 0 receive buffer register
000037	
000038	UART 1 transmit/receive mode register
000039	UART 1 baud rate register (BRG1)
00003A	UART 1 transmission buffer register
00003B	
00003C	UART 1 transmit/receive control register 0
00003D	UART 1 transmit/receive control register 1
00003E	UART 1 receive buffer register
00003F	

Address (Hexadecimal notation)	
000040	Count start flag
000041	
000042	One-shot start flag
000043	
000044	Up-down flag
000045	
000046	Timer A0 register
000047	
000048	Timer A1 register
000049	
00004A	Timer A2 register
00004B	
00004C	Timer A3 register
00004D	
00004E	Timer A4 register
00004F	
000050	Timer B0 register
000051	
000052	Timer B1 register
000053	
000054	Timer B2 register
000055	
000056	Timer A0 mode register
000057	Timer A1 mode register
000058	Timer A2 mode register
000059	Timer A3 mode register
00005A	Timer A4 mode register
00005B	Timer B0 mode register
00005C	Timer B1 mode register
00005D	Timer B2 mode register
00005E	Processor mode register 0
00005F	Processor mode register 1
000060	Watchdog timer register
000061	Watchdog timer frequency selection flag
000062	Reserved area (Note)
000063	Memory allocation control register
000064	UART 2 transmit/receive mode register
000065	UART 2 baud rate register (BRG2)
000066	UART 2 transmission buffer register
000067	
000068	UART 2 transmit/receive control register 0
000069	UART 2 transmit/receive control register 1
00006A	UART 2 receive buffer register
00006B	
00006C	Oscillation circuit control register 0
00006D	Port function control register
00006E	Serial transmit control register
00006F	Oscillation circuit control register 1
000070	A-D/UART 2 trans./rece. interrupt control register
000071	UART 0 transmission interrupt control register
000072	UART 0 receive interrupt control register
000073	UART 1 transmission interrupt control register
000074	UART 1 receive interrupt control register
000075	Timer A0 interrupt control register
000076	Timer A1 interrupt control register
000077	Timer A2 interrupt control register
000078	Timer A3 interrupt control register
000079	Timer A4 interrupt control register
00007A	Timer B0 interrupt control register
00007B	Timer B1 interrupt control register
00007C	Timer B2 interrupt control register
00007D	$\overline{INT_0}$ interrupt control register
00007E	$\overline{INT_1}$ interrupt control register
00007F	$\overline{INT_2}$/Key input interrupt control register

Note. Do not write to this address.

Fig. 2 Location of internal peripheral devices and interrupt control registers

ROM AREA MODIFICATION FUNCTION

The internal ROM size and its address area of the M37736M4BXXXGP can be modified by the memory allocation control register's bit 0 shown in Figure 3.

Figure 5 shows the memory allocation in which the internal ROM size and its address area are modified.

Make sure to write data in the memory allocation control register as the flow shown in Figure 4.

This ROM area modification function is valid in memory expansion mode and single-chip mode.

Table 1 shows the relationship between memory allocation selection bits and address corresponding to chip-select signals $\overline{CS0}$ and $\overline{CS1}$ in the external bus mode B.

When ordering a mask ROM, Mitsubishi Electric corp. produces the mask ROM using the data within 32 Kbytes (addresses 008000_{16} – $00FFFF_{16}$). It is regardless of the selected ROM size (refer to MASK ROM ORDER CONFIRMATION FORM.) Therefore, program "FF_{16}" to the addresses out of the selected ROM area in the EPROM which you tender when ordering a mask ROM.

Address $00FFFF_{16}$ of this microcomputer corresponds to the lowest address of the EPROM which you tender.

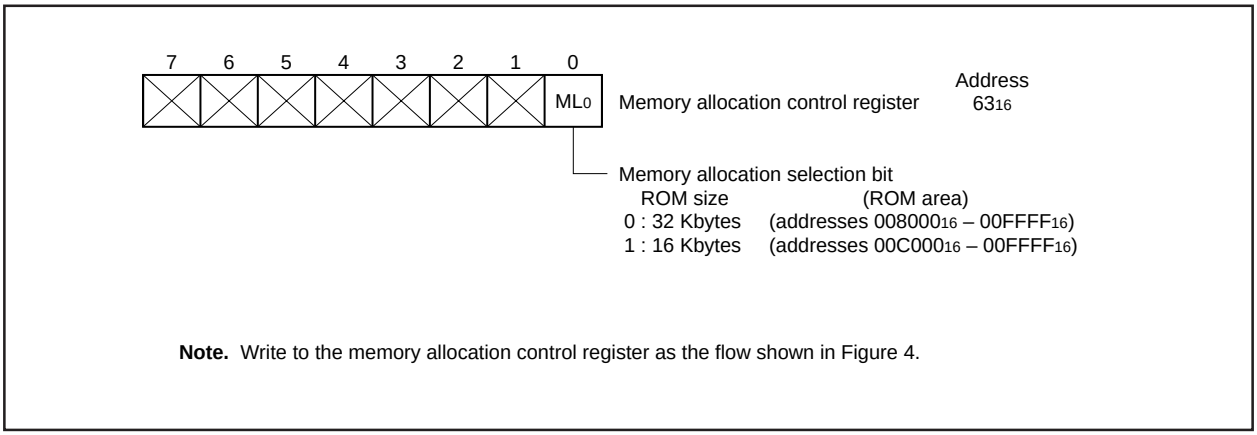


Fig. 3 Bit configuration of memory allocation control register

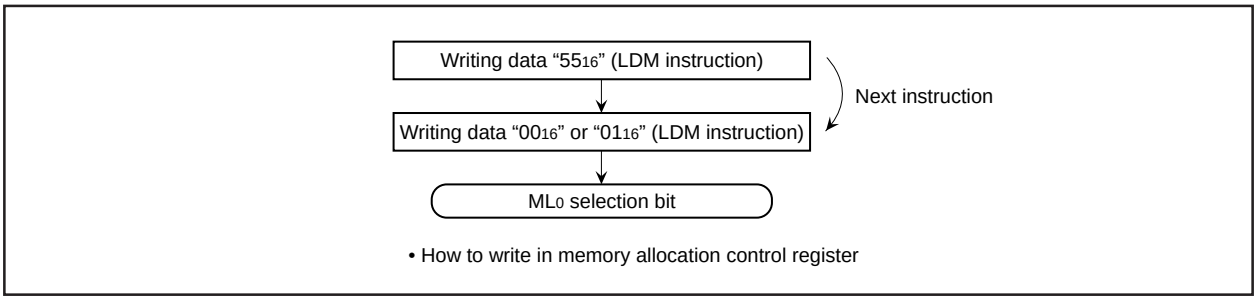
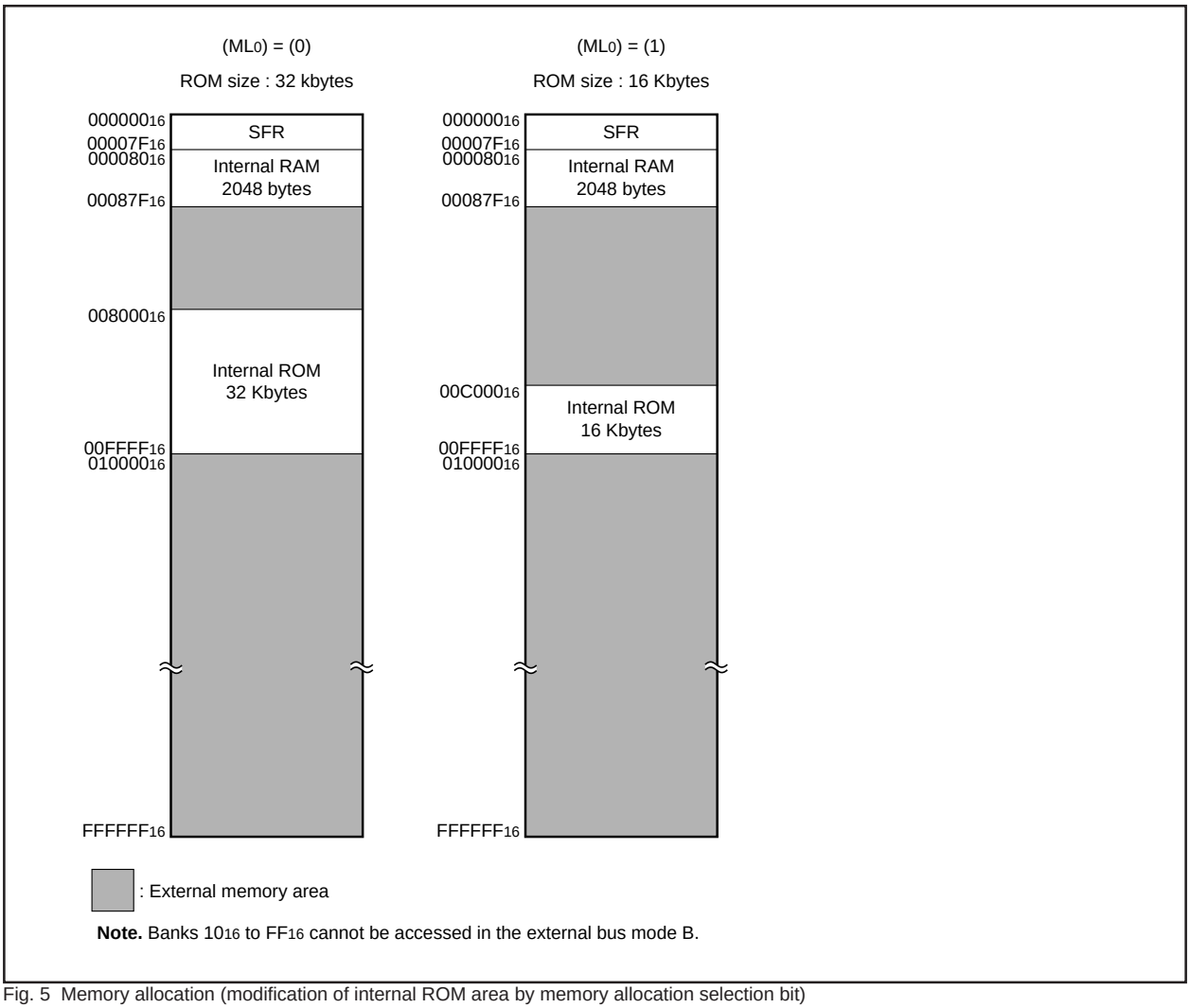


Fig. 4 How to write data in memory allocation control register



Note. Banks 10₁₆ to FF₁₆ cannot be accessed in the external bus mode B.

Fig. 5 Memory allocation (modification of internal ROM area by memory allocation selection bit)

Table 1. Relationship between memory allocation selection bits and addresses corresponding to chip-select signals $\overline{CS_0}$ and $\overline{CS_1}$ in external bus mode B

Memory allocation select bit ML_0	Internal ROM area	Access address	
		$\overline{CS_0}$	$\overline{CS_1}$
0	008000₁₆ – 00FFFF₁₆	000880₁₆ – 007FFF₁₆	010000₁₆ – 03FFFF₁₆
1	00C000₁₆ – 00FFFF₁₆	000880₁₆ – 007FFF₁₆	008000₁₆ – 00BFFF₁₆ 010000₁₆ – 03FFFF₁₆

ADDRESSING MODES

The M37736M4BXXXGP has 28 powerful addressing modes. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE-CHIP 16-BIT MICROCOMPUTERS for the details of each addressing mode.

MACHINE INSTRUCTION LIST

The M37736M4BXXXGP has 103 machine instructions. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE-CHIP 16-BIT MICROCOMPUTERS for details.

DATA REQUIRED FOR MASK ROM ORDERING

Please send the following data for mask orders.
(1) M37736M4BXXXGP mask ROM order confirmation form
(2) 100P6S mark specification form
(3) ROM data (EPROM 3 sets)

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Power source voltage		–0.3 to +7	V
AVcc	Analog power source voltage		–0.3 to +7	V
V_I	Input voltage $\overline{RESET}$, CNVss, BYTE		–0.3 to +12	V
V_I	Input voltage $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_2$, $P10_0$ – $P10_7$, V_{REF}, X_{IN}, BSEL		–0.3 to Vcc + 0.3	V
V_O	Output voltage $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_0$ – $P10_7$, X_{OUT}, E		–0.3 to Vcc + 0.3	V
P_d	Power dissipation	Ta = 25 °C	300	mW
T_{opr}	Operating temperature		–20 to +85	°C
T_{stg}	Storage temperature		–40 to +150	°C

RECOMMENDED OPERATING CONDITIONS (Vcc = 5 V ± 10%, Ta = –20 to +85 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
Vcc	Power source voltage	f(X_{IN}) : Operating	4.5	5.0	5.5	V
		f(X_{IN}) : Stopped, f(X_{CIN}) = 32.768 kHz	2.7		5.5	
AVcc	Analog power source voltage			Vcc		V
Vss	Power source voltage			0		V
AVss	Analog power source voltage			0		V
V_{IH}	High-level input voltage $P0_0$ – $P0_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_2$, $P10_0$ – $P10_7$, X_{IN}, $\overline{RESET}$, CNVss, BYTE, BSEL, X_{CIN} (Note 3)		0.8 Vcc		Vcc	V
V_{IH}	High-level input voltage $P1_0$ – $P1_7$, $P2_0$ – $P2_7$ (in single-chip mode)		0.8 Vcc		Vcc	V
V_{IH}	High-level input voltage $P1_0$ – $P1_7$, $P2_0$ – $P2_7$ (in memory expansion mode and microprocessor mode)		0.5 Vcc		Vcc	V
V_{IL}	Low-level input voltage $P0_0$ – $P0_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_2$, $P10_0$ – $P10_7$, X_{IN}, $\overline{RESET}$, CNVss, BYTE, BSEL, X_{CIN} (Note 3)		0		0.2Vcc	V
V_{IL}	Low-level input voltage $P1_0$ – $P1_7$, $P2_0$ – $P2_7$ (in single-chip mode)		0		0.2Vcc	V
V_{IL}	Low-level input voltage $P1_0$ – $P1_7$, $P2_0$ – $P2_7$ (in memory expansion mode and microprocessor mode)		0		0.16Vcc	V
$I_{OH(peak)}$	High-level peak output current $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_0$ – $P10_7$				–10	mA
$I_{OH(avg)}$	High-level average output current $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_0$ – $P10_7$				–5	mA
$I_{OL(peak)}$	Low-level peak output current $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_3$, $P5_4$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_4$ – $P10_7$				10	mA
$I_{OL(peak)}$	Low-level peak output current $P4_4$ – $P4_7$, $P10_0$ – $P10_3$				20	mA
$I_{OL(avg)}$	Low-level average output current $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_3$, $P5_4$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_4$ – $P10_7$				5	mA
$I_{OL(avg)}$	Low-level average output current $P4_4$ – $P4_7$, $P10_0$ – $P10_3$				15	mA
f(X_{IN})	Main-clock oscillation frequency (Note 4)				25	MHz
f(X_{CIN})	Sub-clock oscillation frequency			32.768	50	kHz

Notes 1. Average output current is the average value of a 100 ms interval.

2. The sum of $I_{OL(peak)}$ for ports P0, P1, P2, P3, P8, and P9 must be 80 mA or less, the sum of $I_{OH(peak)}$ for ports P0, P1, P2, P3, P8, and P9 must be 80 mA or less, the sum of $I_{OL(peak)}$ for ports P4, P5, P6, P7, and P10 must be 100 mA or less, and the sum of $I_{OH(peak)}$ for ports P4, P5, P6, P7, and P10 must be 80 mA or less.

3. Limits V_{IH} and V_{IL} for X_{CIN} are applied when the sub clock external input selection bit = “1”.

4. The maximum value of f(X_{IN}) = 12.5 MHz when the main clock division selection bit = “1”.

ELECTRICAL CHARACTERISTICS (Vcc = 5 V, Vss = 0 V, Ta = –20 to 85 °C, f(X_{IN}) = 25 MHz, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V_{OH}	High-level output voltage $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_0$ – $P10_7$	I_{OH} = –10 mA	3			V
V_{OH}	High-level output voltage $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_3$	I_{OH} = –400 µA	4.7			V
V_{OH}	High-level output voltage $P3_0$ – $P3_2$	I_{OH} = –10 mA	3.1			V
		I_{CH} = –400 µA	4.8			
V_{OH}	High-level output voltage $\overline{E}$	I_{OH} = –10 mA	3.4			V
		I_{OH} = –400 µA	4.8			
V_{OL}	Low-level output voltage $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_3$, $P4_0$ – $P4_3$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_5$, $P8_0$ – $P8_7$, $P9_0$ – $P9_7$, $P10_4$ – $P10_7$	I_{OL} = 10 mA			2	V
V_{OL}	Low-level output voltage $P4_4$ – $P4_7$, $P10_0$ – $P10_3$	I_{OL} = 20 mA			2	V
V_{OL}	Low-level output voltage $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_3$	I_{OL} = 2 mA			0.45	V
V_{OL}	Low-level output voltage $P3_0$ – $P3_2$	I_{OL} = 10 mA			1.9	V
		I_{OL} = 2 mA			0.43	
V_{OL}	Low-level output voltage $\overline{E}$	I_{OL} = 10 mA			1.6	V
		I_{OL} = 2 mA			0.4	
$V_{T+} – V_{T–}$	Hysteresis $\overline{HOLD}$, $\overline{RDY}$, $TA0_{IN}$ – $TA4_{IN}$, $TB0_{IN}$ – $TB2_{IN}$, $\overline{INT_0}$ – $\overline{INT_2}$, $\overline{ADTRG}$, $\overline{CTS_0}$, $\overline{CTS_1}$, $\overline{CTS_2}$, CLK_0, CLK_1, CLK_2, $\overline{KI_0}$ – $\overline{KI_3}$		0.4		1	V
$V_{T+} – V_{T–}$	Hysteresis $\overline{RESET}$		0.2		0.5	V
$V_{T+} – V_{T–}$	Hysteresis X_{IN}		0.1		0.4	V
$V_{T+} – V_{T–}$	Hysteresis X_{CIN} (When external clock is input)		0.1		0.4	V
I_{IH}	High-level input current $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_2$, $P10_0$ – $P10_7$, X_{IN}, $\overline{RESET}$, CNVss, BYTE, BSEL	V_I = 5 V			5	µA
I_{IL}	Low-level input current $P0_0$ – $P0_7$, $P1_0$ – $P1_7$, $P2_0$ – $P2_7$, $P3_0$ – $P3_3$, $P4_0$ – $P4_7$, $P5_0$ – $P5_7$, $P6_0$, $P6_1$, $P6_5$ – $P6_7$, $P7_0$ – $P7_7$, $P8_0$ – $P8_7$, $P9_0$ – $P9_2$, $P10_0$ – $P10_3$, X_{IN}, $\overline{RESET}$, CNVss, BYTE, BSEL	V_I = 0 V			–5	µA
I_{IL}	Low-level input current $P10_4$ – $P10_7$, $P6_2$ – $P6_4$	V_I = 0 V, without a pull-up transistor			–5	µA
		V_I = 0 V, with a pull-up transistor	–0.25	–0.5	–1.0	mA
V_{RAM}	RAM hold voltage	When clock is stopped.	2			V

ELECTRICAL CHARACTERISTICS (Vcc = 5 V, Vss = 0 V, Ta = –20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Test conditions		Limits			Unit
				Min.	Typ.	Max.	
I_{CC}	Power source current	In single-chip mode, output pins are open, and other pins are V_{SS}.	V_{CC} = 5 V, $f(X_{IN})$ = 25 MHz (square waveform), $f(f_2)$ = 12.5 MHz, $f(X_{CIN})$ = 32.768 kHz, in operating (Note 1)		9.5	19	mA
			V_{CC} = 5 V, $f(X_{IN})$ = 25 MHz (square waveform), ($f(f_2)$ = 1.5625 MHz), $f(X_{CIN})$ = Stopped, in operating (Note 1)		1.3	2.6	mA
			V_{CC} = 5V, $f(X_{IN})$ = 25 MHz (square waveform), $f(X_{CIN})$ = 32.768 kHz, when a WIT instruction is executed (Note 2)		10	20	µA
			V_{CC} = 5 V, $f(X_{IN})$: Stopped, $f(X_{CIN})$: 32.768 kHz, in operating (Note 3)		50	100	µA
			V_{CC} = 5 V, $f(X_{IN})$: Stopped, $f(X_{CIN})$: 32.768 kHz, when a WIT instruction is executed (Note 4)		5	10	µA
			Ta = 25 °C, when clock is stopped			1	µA
			Ta = 85 °C, when clock is stopped			20	µA

Notes 1. This applies when the main clock external input selection bit = “1”, the main clock division selection bit = “0”, and the signal output stop bit = “1”.

2. This applies when the main clock external input selection bit = “1” and the system clock stop bit at wait state = “1”.

3. This applies when CPU and the clock timer are operating with the sub clock (32.768 kHz) selected as the system clock.

4. This applies when the X_{COUT} drivability selection bit = “0” and the system clock stop bit at wait state = “1”.

A–D CONVERTER CHARACTERISTICS

(V_{CC} = AV_{CC} = 5 V, V_{SS} = AV_{SS} = 0 V, Ta = –20 to 85 °C, $f(X_{IN})$ = 25 MHz (Note), unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
—	Resolution	V_{REF} = V_{CC}			10	Bits
—	Absolute accuracy	V_{REF} = V_{CC}			± 3	LSB
R_{LADDER}	Ladder resistance	V_{REF} = V_{CC}	10		25	kΩ
t_{CONV}	Conversion time		9.44			µs
V_{REF}	Reference voltage		2		V_{CC}	V
V_{IA}	Analog input voltage		0		V_{REF}	V

Note. This applies when the main clock division selection bit = “0” and $f(f_2)$ = 12.5 MHz.

TIMING REQUIREMENTS (V_{CC} = 5 V ± 10%, V_{SS} = 0 V, Ta = –20 to 85 °C, f(X_{IN}) = 25 MHz, unless otherwise noted (Note))

Notes 1. This applies when the main clock division selection bit = "0" and f(f_2) = 12.5 MHz.

2. Input signal's rise/fall time must be 100 ns or less, unless otherwise noted.

External clock input

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t_c	External clock input cycle time (Note 3)	40		ns
$t_{w(H)}$	External clock input high-level pulse width (Note 4)	15		ns
$t_{w(L)}$	External clock input low-level pulse width (Note 4)	15		ns
t_r	External clock rise time		8	ns
t_f	External clock fall time		8	ns

Notes 3. When the main clock division selection bit = "1", the minimum value of tc = 80 ns.

4. When the main clock division selection bit = "1", values of $t_{w(H)}$ / tc and $t_{w(L)}$ / tc must be set to values from 0.45 through 0.55.

Single-chip mode

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{su(P0D–E)}$	Port P0 input setup time	60		ns
$t_{su(P1D–E)}$	Port P1 input setup time	60		ns
$t_{su(P2D-E)}$	Port P2 input setup time	60		ns
$t_{su(P3D–E)}$	Port P3 input setup time	60		ns
$t_{su(P4D–E)}$	Port P4 input setup time	60		ns
$t_{su(P5D–E)}$	Port P5 input setup time	60		ns
$t_{su(P6D–E)}$	Port P6 input setup time	60		ns
$t_{su(P7D–E)}$	Port P7 input setup time	60		ns
$t_{su(P8D–E)}$	Port P8 input setup time	60		ns
$t_{su(P10D–E)}$	Port P10 input setup time	60		ns
$t_{h(E–P0D)}$	Port P0 input hold time	0		ns
$t_{h(E–P1D)}$	Port P1 input hold time	0		ns
$t_{h(E–P2D)}$	Port P2 input hold time	0		ns
$t_{h(E–P3D)}$	Port P3 input hold time	0		ns
$t_{h(E–P4D)}$	Port P4 input hold time	0		ns
$t_{h(E–P5D)}$	Port P5 input hold time	0		ns
$t_{h(E–P6D)}$	Port P6 input hold time	0		ns
$t_{h(E–P7D)}$	Port P7 input hold time	0		ns
$t_{h(E–P8D)}$	Port P8 input hold time	0		ns
$t_{h(E–P10D)}$	Port P10 input hold time	0		ns

Memory expansion mode and microprocessor mode

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{su(D–E)}$	Data input setup time (external bus mode A)	32		ns
$t_{su(D–RDE)}$	Data input setup time (external bus mode B)	32		ns
$t_{su(RDY–\phi1)}$	$\overline{RDY}$ input setup time	55		ns
$t_{su(HOLD–\phi1)}$	$\overline{HOLD}$ input setup time	55		ns
$t_{h(E–D)}$	Data input hold time (external bus mode A)	0		ns
$t_{h(RDE–D)}$	Data input hold time (external bus mode B)	0		ns
$t_{h(\phi1–RDY)}$	$\overline{RDY}$ input hold time	0		ns
$t_{h(\phi1–HOLD)}$	$\overline{HOLD}$ input hold time	0		ns

Timer A input (Count input in event counter mode)

Symbol	parameter	Limits		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	80		ns
$t_{w(TAH)}$	TAiIN input high-level pulse width	40		ns
$t_{w(TAL)}$	TAiIN input low-level pulse width	40		ns

Timer A input (Gating input in timer mode)

Symbol	parameter	Limits		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time (Note)	320		ns
$t_{w(TAH)}$	TAiIN input high-level pulse width (Note)	160		ns
$t_{w(TAL)}$	TAiIN input low-level pulse width (Note)	160		ns

Note. Limits change depending on f(X_{IN}). Refer to “DATA FORMULAS”.

Timer A input (External trigger input in one-shot pulse mode)

Symbol	parameter	Limits		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time (Note)	320		ns
$t_{w(TAH)}$	TAiIN input high-level pulse width	80		ns
$t_{w(TAL)}$	TAiIN input low-level pulse width	80		ns

Note. Limits change depending on f(X_{IN}). Refer to “DATA FORMULAS”.

Timer A input (External trigger input in pulse width modulation mode)

Symbol	parameter	Limits		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN input high-level pulse width	80		ns
$t_{w(TAL)}$	TAiIN input low-level pulse width	80		ns

Timer A input (Up-down input in event counter mode)

Symbol	parameter	Limits		Unit
		Min.	Max.	
$t_{c(UP)}$	TAiOUT input cycle time	2000		ns
$t_{w(UPH)}$	TAiOUT input high-level pulse width	1000		ns
$t_{w(UPL)}$	TAiOUT input low-level pulse width	1000		ns
$t_{su(UP-TIN)}$	TAiOUT input setup time	400		ns
$t_{h(TIN-UP)}$	TAiOUT input hold time	400		ns

Timer A input (Two-phase pulse input in event counter mode)

Symbol	parameter	Limits		Unit
		Min.	Max.	
$t_{c(TA)}$	TAjIN input cycle time	800		ns
$t_{su(TAjIN-TAjOUT)}$	TAjIN input setup time	200		ns
$t_{su(TAjOUT-TAjIN)}$	TAjOUT input setup time	200		ns

Timer B input (Count input in event counter mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (one edge count)	80		ns
$t_{w(TBH)}$	TBiIN input high-level pulse width (one edge count)	40		ns
$t_{w(TBL)}$	TBiIN input low-level pulse width (one edge count)	40		ns
$t_{c(TB)}$	TBiIN input cycle time (both edges count)	160		ns
$t_{w(TBH)}$	TBiIN input high-level pulse width (both edges count)	80		ns
$t_{w(TBL)}$	TBiIN input low-level pulse width (both edges count)	80		ns

Timer B input (Pulse period measurement mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (Note)	320		ns
$t_{w(TBH)}$	TBiIN input high-level pulse width (Note)	160		ns
$t_{w(TBL)}$	TBiIN input low-level pulse width (Note)	160		ns

Note. Limits change depending on f(XIN). Refer to “DATA FORMULAS”.

Timer B input (Pulse width measurement mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (Note)	320		ns
$t_{w(TBH)}$	TBiIN input high-level pulse width (Note)	160		ns
$t_{w(TBL)}$	TBiIN input low-level pulse width (Note)	160		ns

Note. Limits change depending on f(XIN). Refer to “DATA FORMULAS”.

A-D trigger input

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(AD)}$	$\overline{ADTRG}$ input cycle time (minimum allowable trigger)	1000		ns
$t_{w(ADL)}$	$\overline{ADTRG}$ input low-level pulse width	125		ns

Serial I/O

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_{w(CKH)}$	CLKi input high-level pulse width	100		ns
$t_{w(CKL)}$	CLKi input low-level pulse width	100		ns
$t_{d(C-Q)}$	TxDi output delay time		80	ns
$t_{h(C-Q)}$	TxDi hold time	0		ns
$t_{su(D-C)}$	RxDi input setup time	30		ns
$t_{h(C-D)}$	RxDi input hold time	90		ns

External interrupt $\overline{INT_i}$ input, key input interrupt $\overline{KI_i}$ input

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT_i}$ input high-level pulse width	250		ns
$t_{w(INL)}$	$\overline{INT_i}$ input low-level pulse width	250		ns
$t_{w(KIL)}$	$\overline{KI_i}$ input low-level pulse width	250		ns

DATA FORMULAS

Timer A input (Gating input in timer mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(TA)}$	TAi$_{IN}$ input cycle time	$\frac{8 \times 10^9}{2 \cdot f(f_2)}$		ns
$t_{w(TAH)}$	TAi$_{IN}$ input high-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns
$t_{w(TAL)}$	TAi$_{IN}$ input low-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns

Timer A input (External trigger input in one-shot pulse mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(TA)}$	TAi$_{IN}$ input cycle time	$\frac{8 \times 10^9}{2 \cdot f(f_2)}$		ns

Timer B input (In pulse period measurement mode or pulse width measurement mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(TB)}$	TBi$_{IN}$ input cycle time	$\frac{8 \times 10^9}{2 \cdot f(f_2)}$		ns
$t_{w(TBH)}$	TBi$_{IN}$ input high-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns
$t_{w(TBL)}$	TBi$_{IN}$ input low-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns

Note. $f(f_2)$ represents the clock f_2 frequency.
For the relation to the main clock and sub clock, refer to Table 10 in data sheet “M37736MHBXXXGP”.

SWITCHING CHARACTERISTICS (V_{CC} = 5 V ± 10%, V_{SS} = 0 V, Ta = –20 to 85°C, f(X_{IN}) = 25 MHz (Note), unless otherwise noted)

Symbol	Parameter	Test conditions	Limits		Unit
			Min.	Max.	
$t_{d(E-P0Q)}$	Port P0 data output delay time	Fig. 6		80	ns
$t_{d(E-P1Q)}$	Port P1 data output delay time			80	ns
$t_{d(E-P2Q)}$	Port P2 data output delay time			80	ns
$t_{d(E-P3Q)}$	Port P3 data output delay time			80	ns
$t_{d(E-P4Q)}$	Port P4 data output delay time			80	ns
$t_{d(E-P5Q)}$	Port P5 data output delay time			80	ns
$t_{d(E-P6Q)}$	Port P6 data output delay time			80	ns
$t_{d(E-P7Q)}$	Port P7 data output delay time			80	ns
$t_{d(E-P8Q)}$	Port P8 data output delay time			80	ns
$t_{d(E-P9Q)}$	Port P9 data output delay time			80	ns
$t_{d(E-P10Q)}$	Port P10 data output delay time			80	ns

Note. This applies when the main clock division selection bit = “0” and f(f_2) = 12.5 MHz.

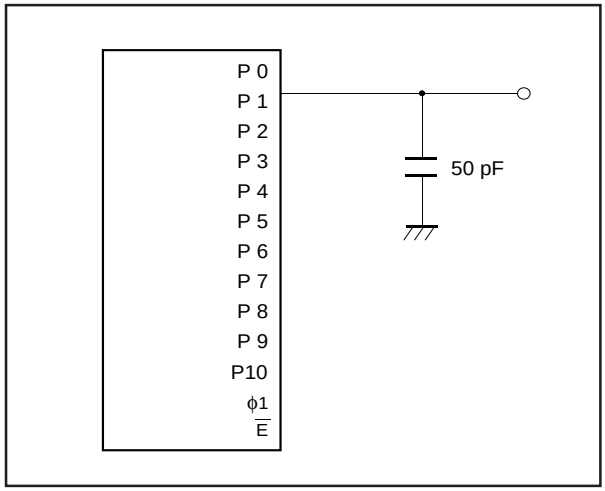


Fig. 6 Measuring circuit for ports P0 – P10 and ϕ_1

[External bus mode A]

Memory expansion mode and microprocessor mode

(V_{CC} = 5 V ± 10%, V_{SS} = 0 V, Ta = 25 °C, f(X_{IN}) = 25 MHz (Note 1), unless otherwise noted)

Symbol	Parameter	(Note 2) Wait mode	Test conditions	Limits Min.	Limits Max.	Unit
$t_{d(An-E)}$	Address output delay time	No wait Wait 1		12		ns
		Wait 0	Fig. 6	87		ns
$t_{d(A-E)}$	Address output delay time	No wait Wait 1		12		ns
		Wait 0		75		ns
$t_{h(E-An)}$	Address hold time			18		ns
$t_{w(ALE)}$	ALE pulse width	No wait Wait 1		22		ns
		Wait 0		57		ns
$t_{su(A-ALE)}$	Address output setup time	No wait Wait 1		5		ns
		Wait 0		45		ns
$t_{h(ALE-A)}$	Address hold time	No wait Wait 1		9		ns
		Wait 0		15		ns
$t_{d(ALE-E)}$	ALE output delay time	No wait Wait 1		4		ns
		Wait 0		10		ns
$t_{d(E-DQ)}$	Data output delay time				45	ns
$t_{h(E-DQ)}$	Data hold delay time			18		ns
$t_{w(EL)}$	$\overline{E}$ pulse width	No wait		50		ns
		Wait 1 Wait 0		130		ns
$t_{pxz(E-DZ)}$	Floating start delay time				5	ns
$t_{pzx(E-DZ)}$	Floating release delay time			20		ns
$t_{d(BHE-E)}$	$\overline{BHE}$ output delay time	No wait Wait 1		12		ns
		Wait 0		87		ns
$t_{d(R/W-E)}$	R/$\overline{W}$ output delay time	No wait Wait 1		12		ns
		Wait 0		87		ns
$t_{h(E-BHE)}$	$\overline{BHE}$ hold time			18		ns
$t_{h(E-R/W)}$	R/$\overline{W}$ hold time			18		ns
$t_{d(E-\phi1)}$	ϕ_1 output delay time			0	18	ns
$t_{d(\phi1-HLDA)}$	$\overline{HLDA}$ output delay time				50	ns

Notes 1. This applies when the main clock division selection bit = “0” and f(f_2) = 12.5 MHz.

2. No wait : Wait bit = “1”.
Wait 1 : The external memory area is accessed with wait bit = “0” and wait selection bit = “1”.
Wait 0 : The external memory area is accessed with wait bit = “0” and wait selection bit = “0”.

[External bus mode A]

Memory expansion mode and microprocessor mode

Bus timing data formulas (V_{CC} = 5 V ± 10%, V_{SS} = 0 V, Ta = –20 to 85 °C, f(X_{IN}) = 25 MHz (Max., Note), unless otherwise noted)

Symbol	Parameter	Wait mode	Limits Min.	Limits Max.	Unit
$t_{d(An-E)}$	Address output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
$t_{d(A-E)}$	Address output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 45$		ns
$t_{h(E-An)}$	Address hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
$t_{w(ALE)}$	ALE pulse width	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 18$		ns
		Wait 0	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 23$		ns
$t_{su(A-ALE)}$	Address output setup time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 35$		ns
		Wait 0	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 35$		ns
$t_{h(ALE-A)}$	Address hold time	No wait Wait 1	9		ns
		Wait 0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 25$		ns
$t_{d(ALE-E)}$	ALE output delay time	No wait Wait 1	4		ns
		Wait 0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
$t_{d(E-DQ)}$	Data output delay time			45	ns
$t_{h(E-DQ)}$	Data hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
$t_{w(EL)}$	$\overline{E}$ pulse width	No wait	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
		Wait 1 Wait 0	$\frac{4 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
$t_{pxz(E-DZ)}$	Floating start delay time			5	ns
$t_{pzx(E-DZ)}$	Floating release delay time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 20$		ns
$t_{d(BHE-E)}$	$\overline{BHE}$ output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
$t_{d(R/W-E)}$	R/$\overline{W}$ output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
$t_{h(E-BHE)}$	$\overline{BHE}$ hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
$t_{h(E-R/W)}$	R/$\overline{W}$ hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
$t_{d(E-\phi1)}$	ϕ_1 output delay time		0	18	ns

Notes 1. This applies when the main-clock division selection bit = “0”.

2. f(f_2) represents the clock f_2 frequency.
For the relation to the main clock and sub clock, refer to Table 10 in data sheet “M37736MHBXXXGP”.

[External bus mode B]

Memory expansion mode and microprocessor mode

(V_{CC} = 5 V ± 10%, V_{SS} = 0 V, Ta = –20 to 85 °C, f(X_{IN}) = 25 MHz (Note 1), unless otherwise noted)

Symbol	Parameter	(Note 2) Wait mode	Test conditions	Limits Min.	Limits Max.	Unit
$t_{d(CS-WE)}$ $t_{d(CS-RDE)}$	Chip-select output delay time	No wait / Wait 1	Fig. 6	12		ns
		Wait 0		87		ns
$t_{h(WE-CS)}$ $t_{h(RDE-CS)}$	Chip-select hold time			4		ns
$t_{d(An-WE)}$ $t_{d(An-RDE)}$	Address output delay time	No wait / Wait 1		12		ns
		Wait 0		87		ns
$t_{d(A-WE)}$ $t_{d(A-RDE)}$	Address output delay time	No wait / Wait 1		12		ns
		Wait 0		75		ns
$t_{h(WE-An)}$ $t_{h(RDE-An)}$	Address hold time			18		ns
$t_{w(ALE)}$	ALE pulse width	No wait / Wait 1		22		ns
		Wait 0		57		ns
$t_{su(A-ALE)}$	Address output setup time	No wait / Wait 1		5		ns
		Wait 0		45		ns
$t_{h(ALE-A)}$	Address hold time	No wait / Wait 1		9		ns
		Wait 0		15		ns
$t_{d(ALE-WE)}$ $t_{d(ALE-RDE)}$	ALE output delay time	No wait / Wait 1		4		ns
		Wait 0		10		ns
$t_{d(WE-DQ)}$	Data output delay time				45	ns
$t_{h(WE-DQ)}$	Data hold delay time			18		ns
$t_{w(WE)}$	$\overline{WEL}$/$\overline{WEH}$ pulse width	No wait		50		ns
		Wait 1 / Wait 0		130		ns
$t_{pxz(RDE-DZ)}$	Floating start delay time				5	ns
$t_{pzx(RDE-DZ)}$	Floating release delay time			20		ns
$t_{w(RDE)}$	$\overline{RDE}$ pulse width	No wait		48		ns
		Wait 1 / Wait 0		128		ns
$t_{d(RSMP-WE)}$ $t_{d(RSMP-RDE)}$	$\overline{RSMP}$ output delay time			10		ns
$t_{h(\phi1-RSMP)}$	$\overline{RSMP}$ hold time			0		ns
$t_{d(WE-\phi1)}$ $t_{d(RDE-\phi1)}$	ϕ_1 output delay time			0	18	ns
$t_{d(\phi1-HLDA)}$	$\overline{HLDA}$ output delay time				50	ns

Notes 1. This applies when the main clock division selection bit = “0” and f(f_2) = 12.5 MHz.

2. No wait : Wait bit = “1”.
Wait 1 : The external memory area is accessed with wait bit = “0” and wait selection bit = “1”.
Wait 0 : The external memory area is accessed with wait bit = “0” and wait selection bit = “0”.

[External bus mode B]

Memory expansion mode and microprocessor mode

Bus timing data formulas (V_{CC} = 5 V ± 10%, V_{SS} = 0 V, Ta = –20 to 85 °C, f(X_{IN}) = 25 MHz (Max., Note1), unless otherwise noted)

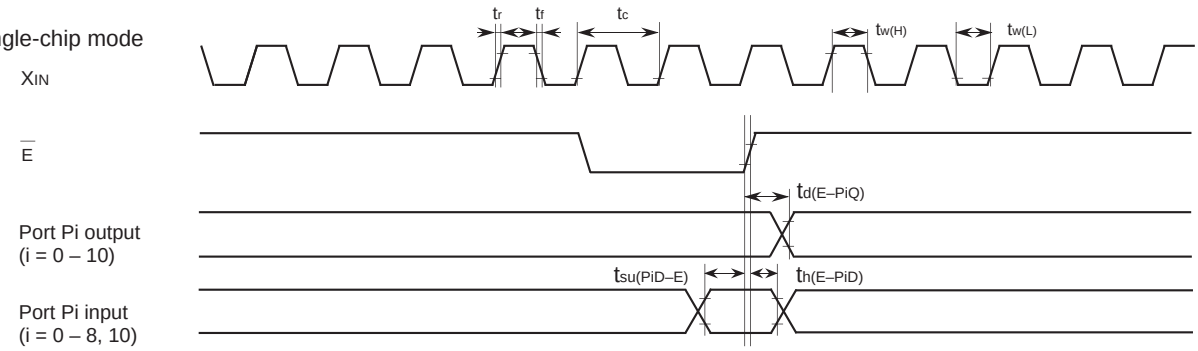
Symbol	Parameter	Wait mode	Limits Min.	Limits Max.	Unit
$t_{d(CS–WE)}$ $t_{d(CS–RDE)}$	Chip-select output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
$t_{h(WE–CS)}$ $t_{h(RDE–CS)}$	Chip-select hold time		4		ns
$t_{d(An–WE)}$ $t_{d(An–RDE)}$	Address output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
$t_{d(A–WE)}$ $t_{d(A–RDE)}$	Address output delay time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 45$		ns
$t_{h(WE–An)}$ $t_{h(RDE–An)}$	Address hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
$t_{w(ALE)}$	ALE pulse width	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 18$		ns
		Wait 0	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 23$		ns
$t_{su(A–ALE)}$	Address output setup time	No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 35$		ns
		Wait 0	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 35$		ns
$t_{h(ALE–A)}$	Address hold time	No wait Wait 1	9		ns
		Wait 0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 25$		ns
$t_{d(ALE–WE)}$ $t_{d(ALE–RDE)}$	ALE output delay time	No wait Wait 1	4		ns
		Wait 0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
$t_{d(WE–DQ)}$	Data output delay time			45	ns
$t_{h(WE–DQ)}$	Data hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
$t_{w(WE)}$	$\overline{WEL}$/$\overline{WEH}$ pulse width	No wait	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
		Wait 1 Wait 0	$\frac{4 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
$t_{pxz(RDE–DZ)}$	Floating start delay time			5	ns
$t_{pzx(RDE–DZ)}$	Floating release delay time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 20$		ns
$t_{w(RDE)}$	$\overline{RDE}$ pulse width	No wait	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 32$		ns
		Wait 1 Wait 0	$\frac{4 \times 10^9}{2 \cdot f(f_2)} - 32$		ns
$t_{d(RSMP–WE)}$ $t_{d(RSMP–RDE)}$	$\overline{RSMP}$ output delay time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
$t_{h(\phi1–RSMP)}$	$\overline{RSMP}$ hold time		0		ns
$t_{d(WE–\phi1)}$ $t_{d(RDE–\phi1)}$	ϕ_1 output delay time		0	18	ns

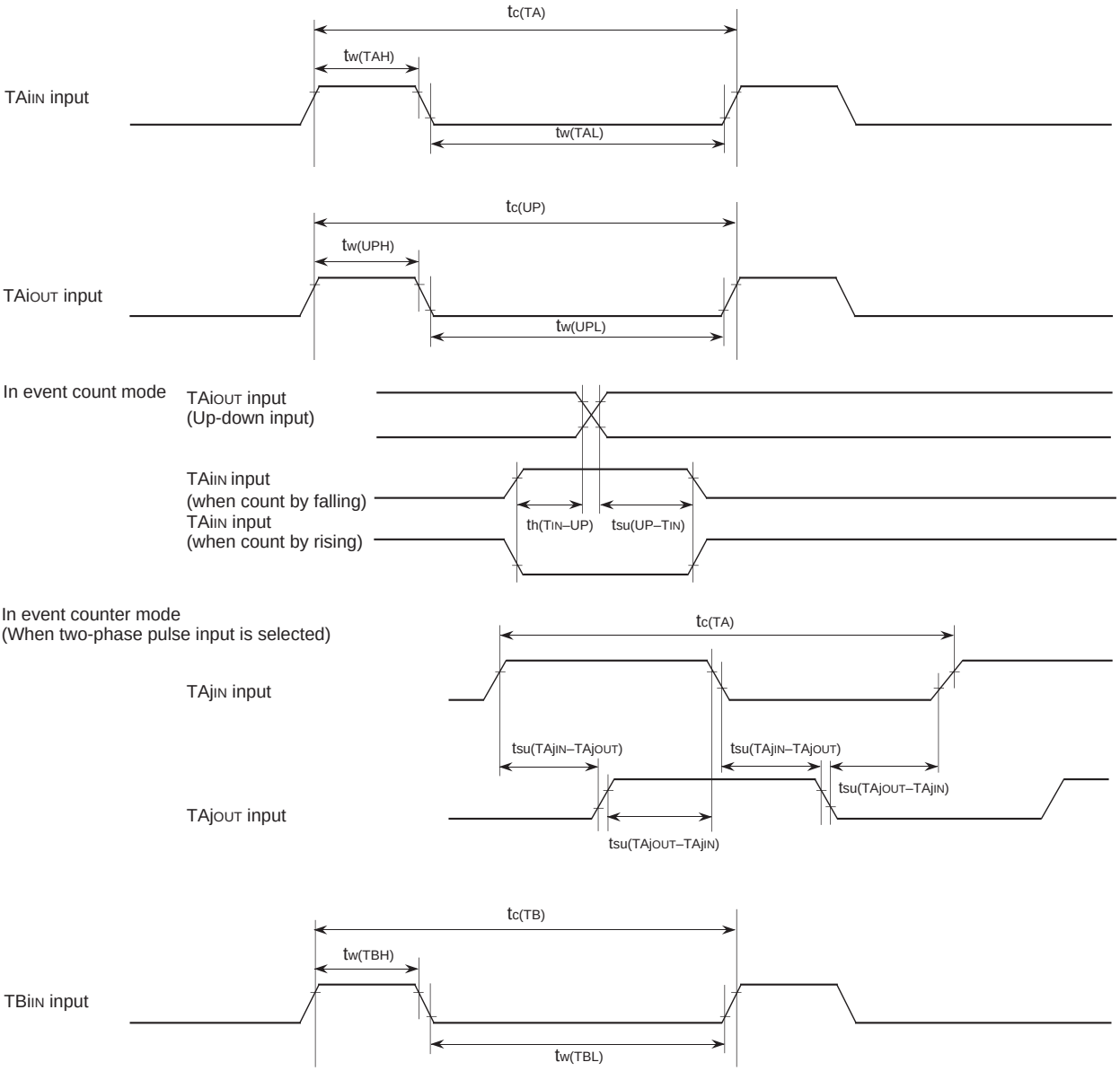
Notes 1. This applies when the main-clock division selection bit = “0”.

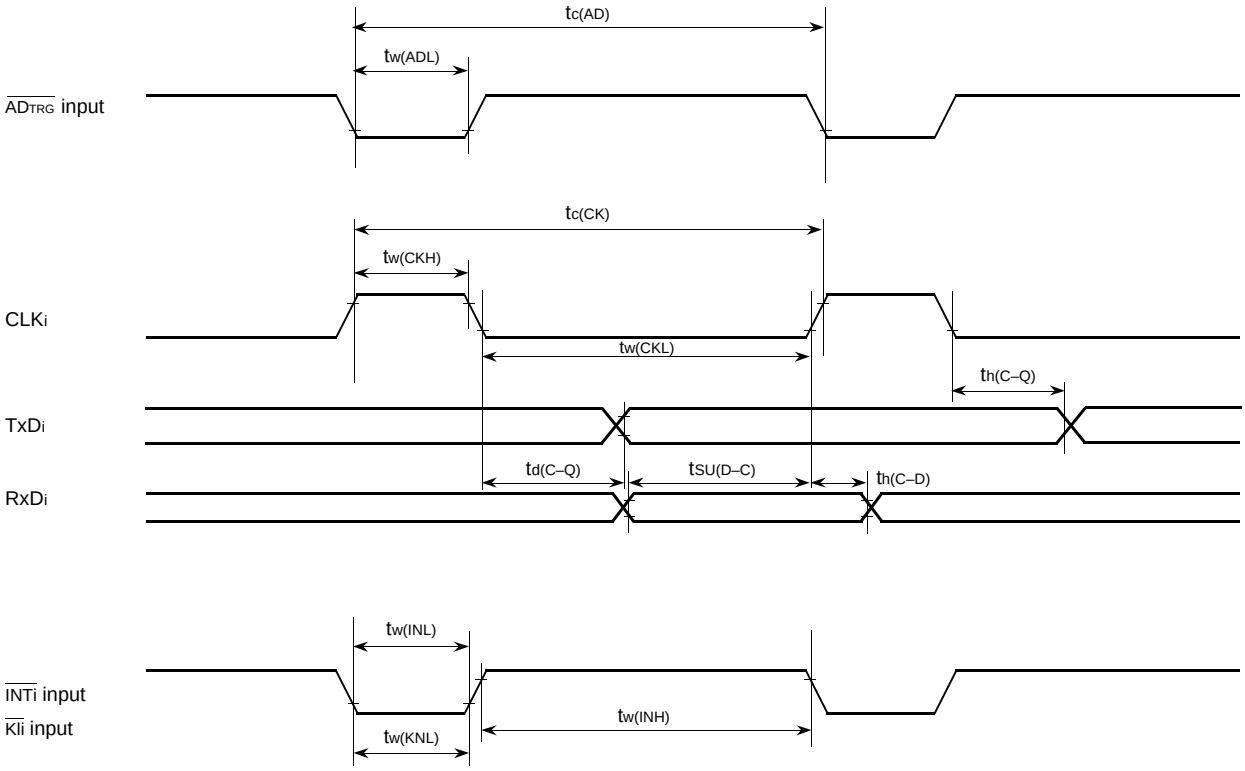
2. f(f_2) represents the clock f_2 frequency.
For the relation to the main clock and sub clock, refer to Table 10 in data sheet “M37736MHBXXXGP”.

TIMING DIAGRAM

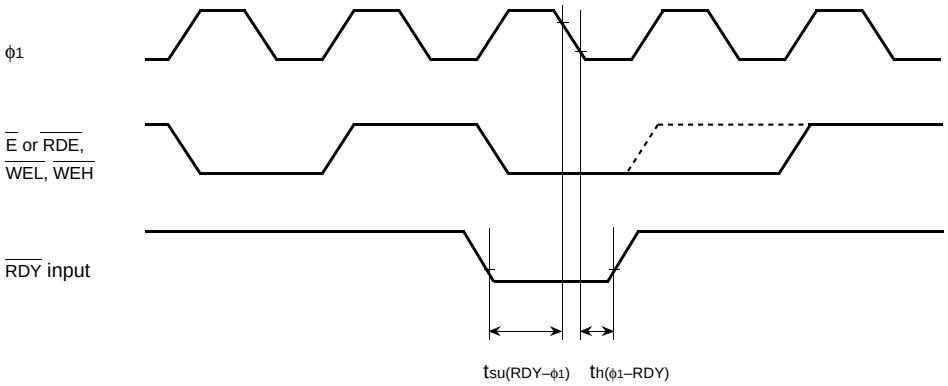
Single-chip mode



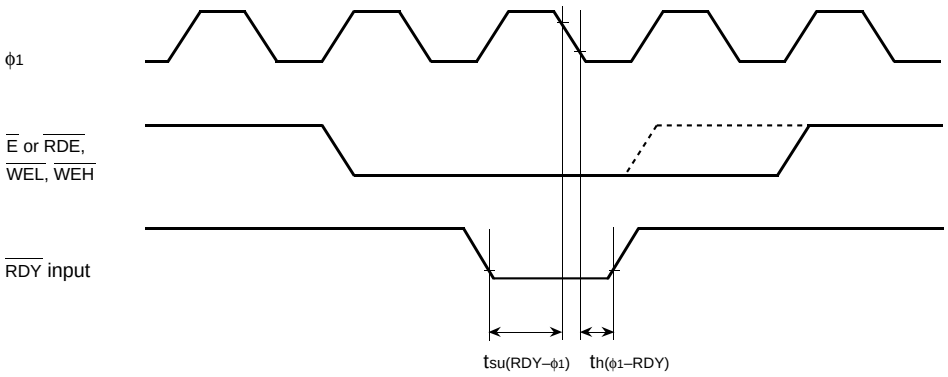

tc(TA)
tw(TAH)
TAiIN input
tw(TAL)
tc(UP)
tw(UPH)
TAiOUT input
tw(UPL)
In event count mode
TAiOUT input
(Up-down input)
TAiIN input
(when count by falling)
TAiIN input
(when count by rising)
th(TIN–UP)
tsu(UP–TIN)
In event counter mode
(When two-phase pulse input is selected)
tc(TA)
TAjIN input
tsu(TAjIN–TAjOUT)
tsu(TAjIN–TAjOUT)
tsu(TAjOUT–TAjIN)
TAjOUT input
tsu(TAjOUT–TAjIN)
tc(TB)
tw(TBH)
TBiIN input
tw(TBL)


tc(AD)
tw(ADL)
ADTRG input
tc(CK)
tw(CKH)
CLKi
tw(CKL)
th(C–Q)
TxDi
td(C–Q)
tSU(D–C)
th(C–D)
RxDi
tw(INL)
INTi input
tw(INH)
Kli input
tw(KNL)

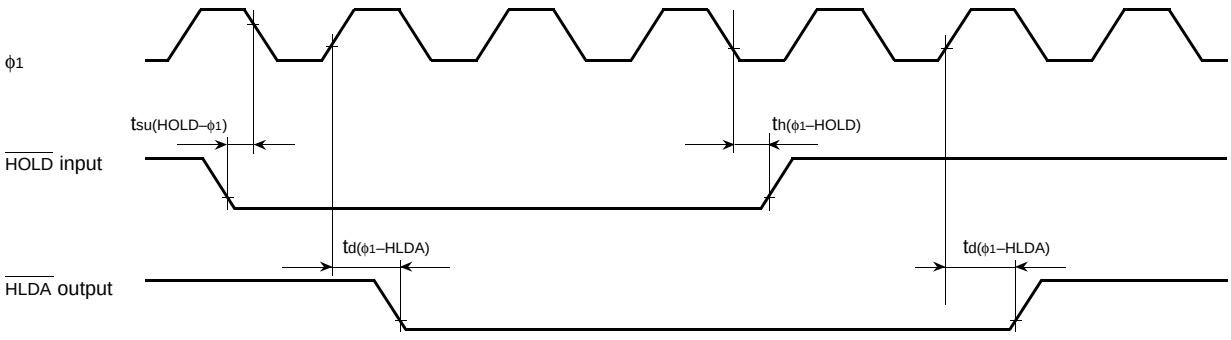
Memory expansion mode and microprocessor mode
(When wait bit = “1”)



(When wait bit = “0”)



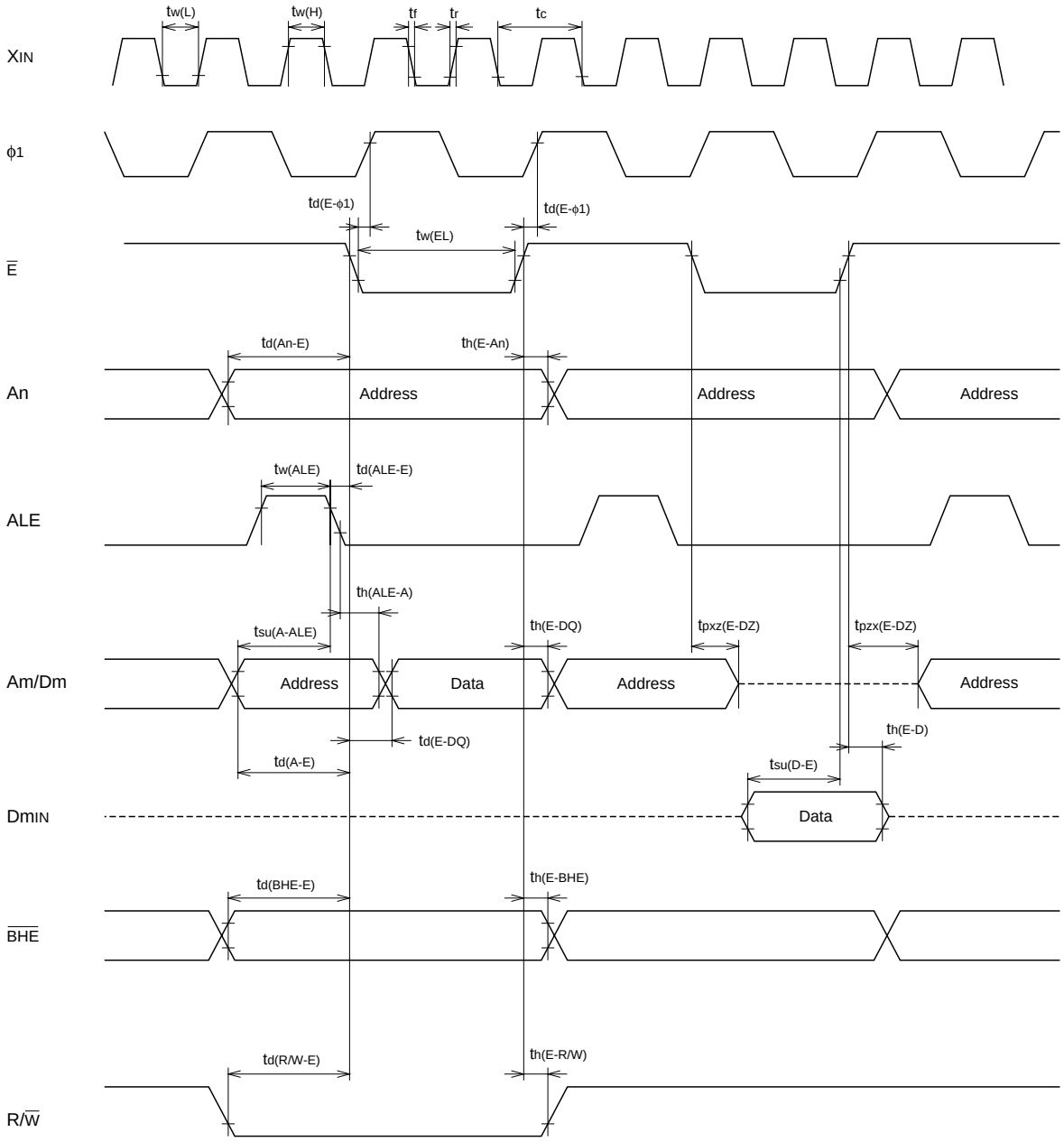
(When wait bit = “1” or “0” in common)



Test conditions
- V_{CC} = 5 V ± 10%
- Input timing voltage : V_{IL} = 1.0 V, V_{IH} = 4.0 V
- Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V

[External bus mode A]

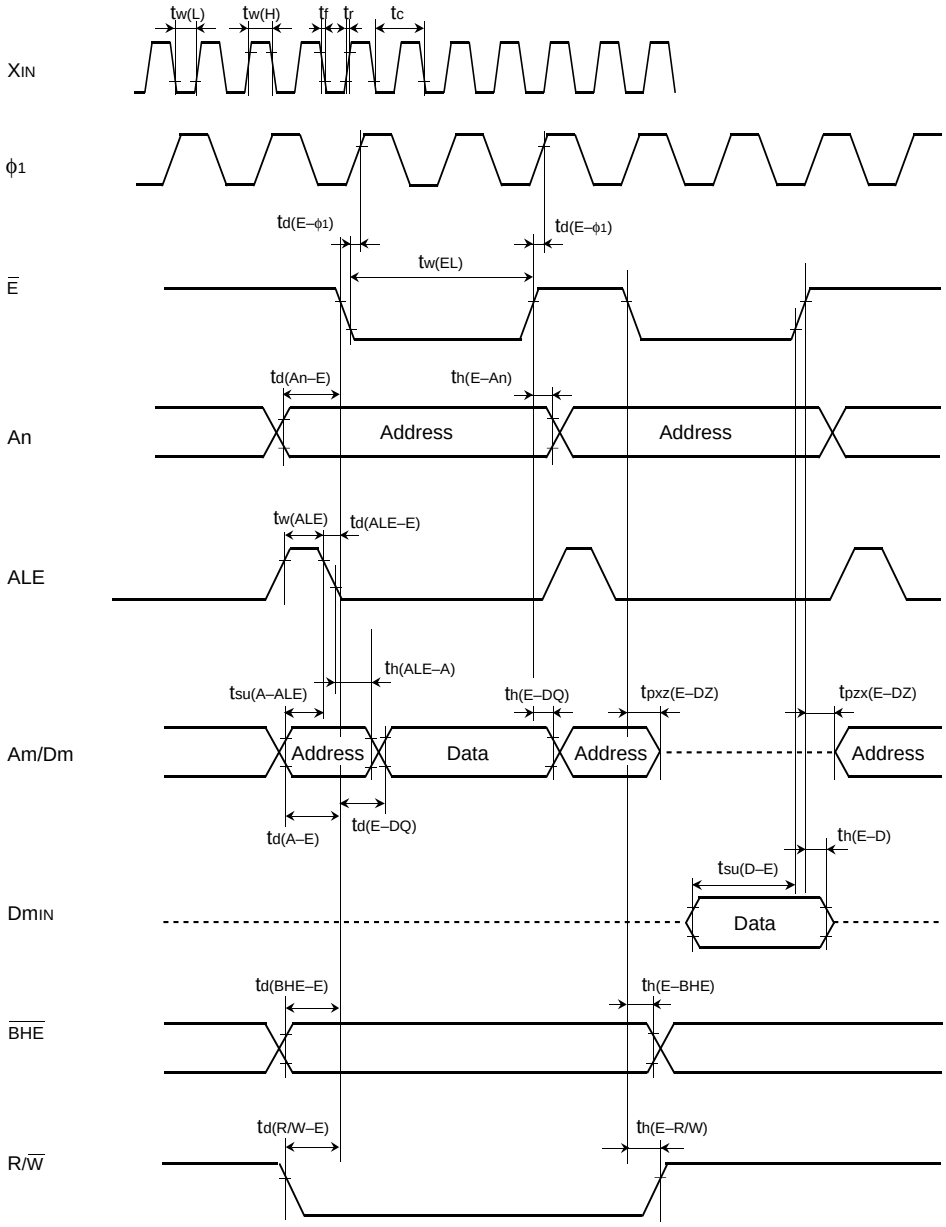
Memory expansion mode and microprocessor mode
(No wait : When wait bit = "1")



Test conditions
・V_{CC} = 5 V ± 10%
・Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V
・Data input Dm_{IN} : V_{IL} = 0.8 V, V_{IH} = 2.5 V

[External bus mode A]

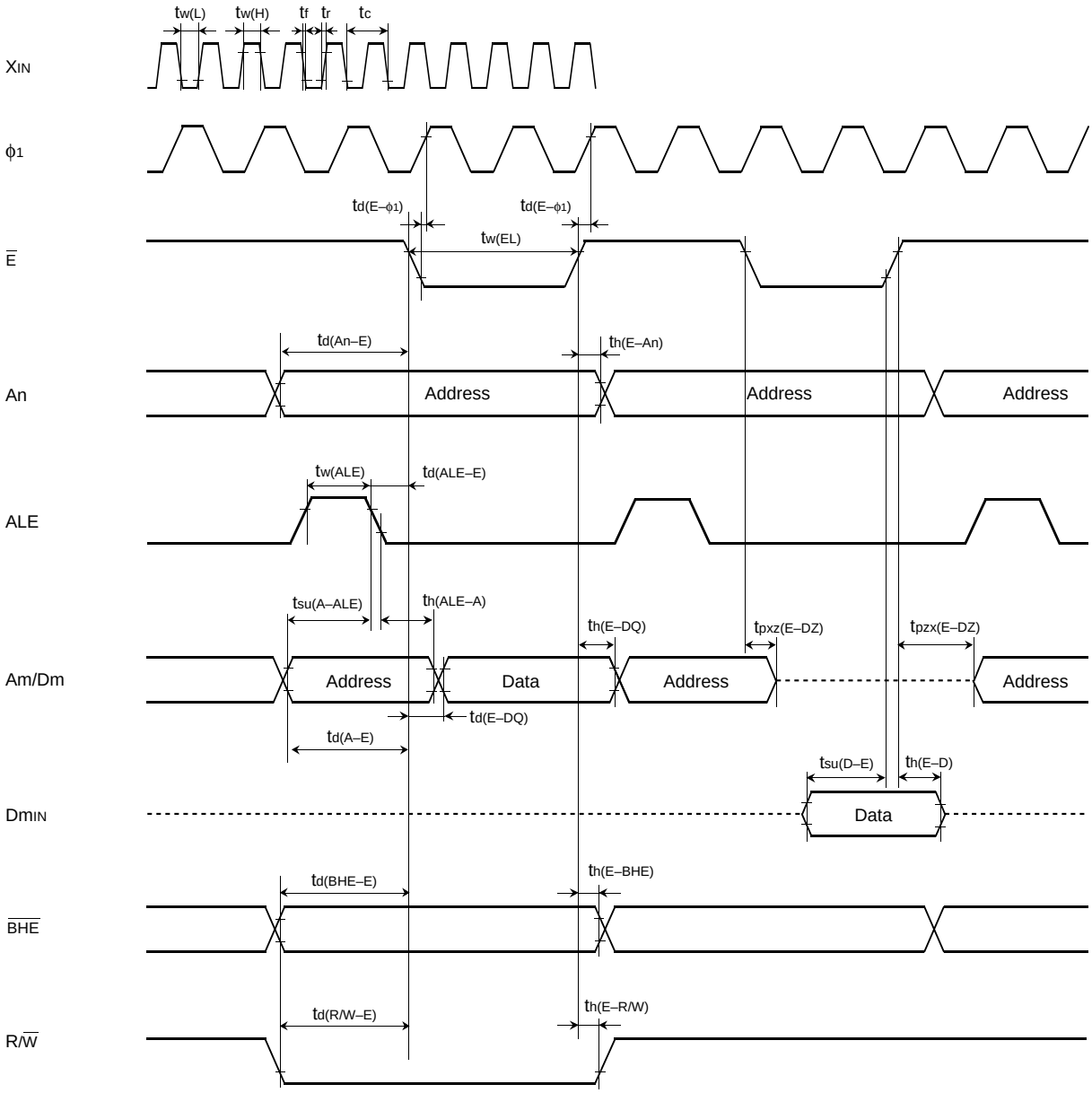
Memory expansion mode and microprocessor mode
(Wait 1 : The external area is accessed when wait bit = “0” and wait selection = “1”.)



Test conditions
- Vcc = 5 V ± 10%
- Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V
- Data input Dm_{IN} : V_{IL} = 0.8 V, V_{IH} = 2.5 V

[External bus mode A]

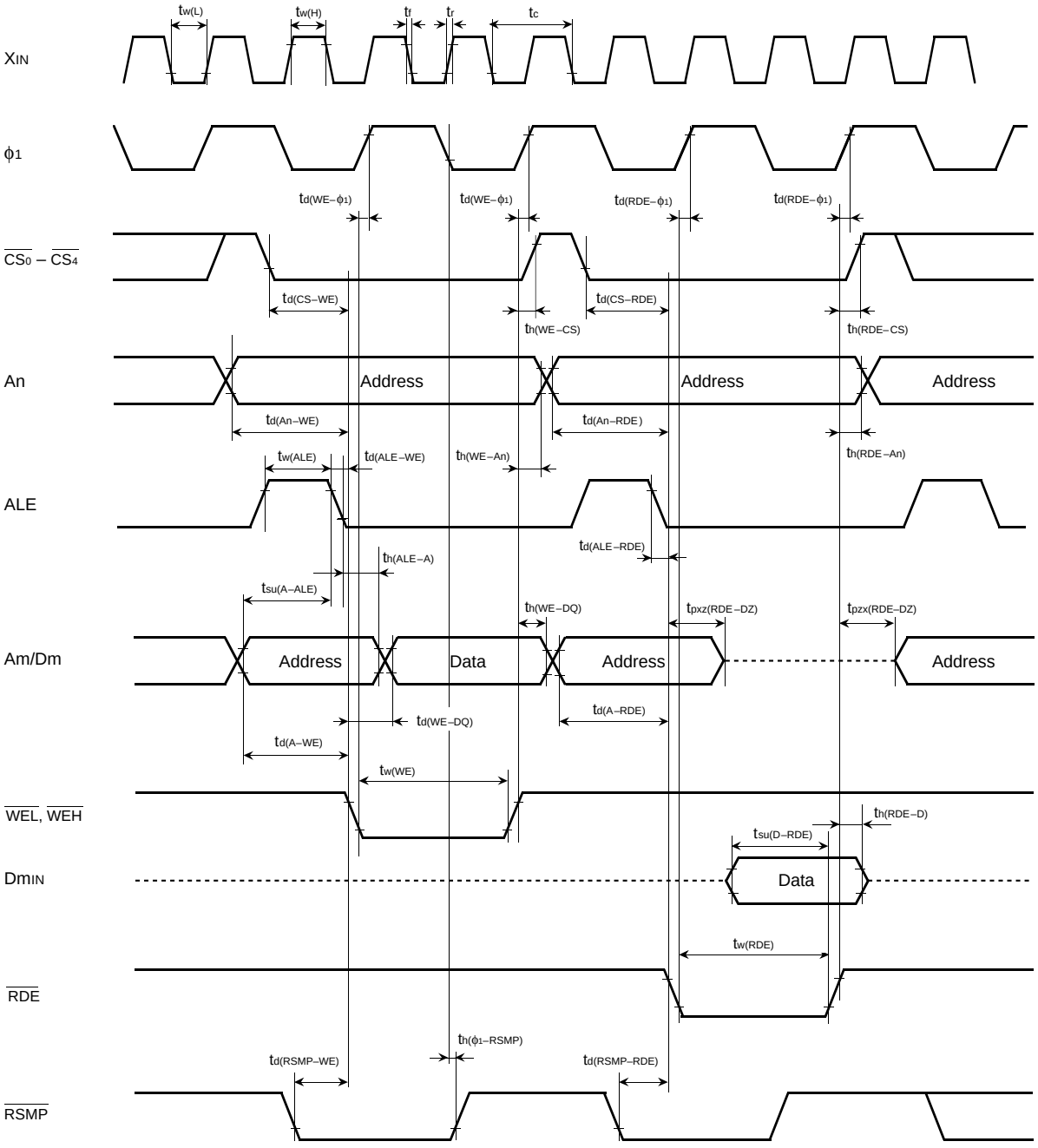
Memory expansion mode and microprocessor mode
(Wait 0 : The external memory area is accessed when wait bit = “0” and wait selection bit = “0”.)



Test conditions
- Vcc = 5 V ± 10%
- Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V
- Data input Dm_{IN} : V_{IL} = 0.8 V, V_{IH} = 2.5 V

[External bus mode B]

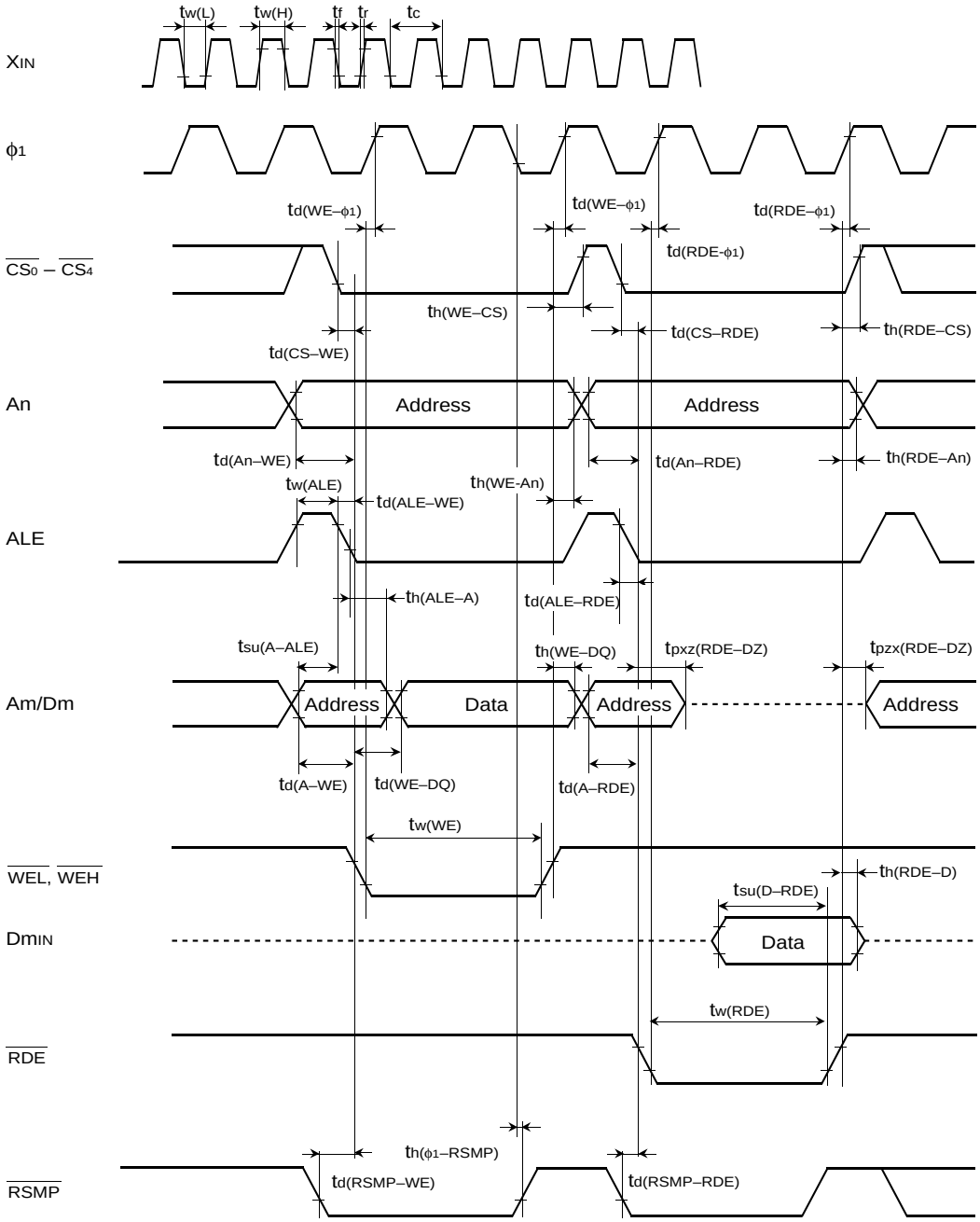
Memory expansion mode and microprocessor mode
(No wait : When wait bit = "1")



Test conditions
- Vcc = 5 V ± 10%
- Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V
- Data input Dm_{IN} : V_{IL} = 0.8 V, V_{IH} = 2.5 V

[External bus mode B]

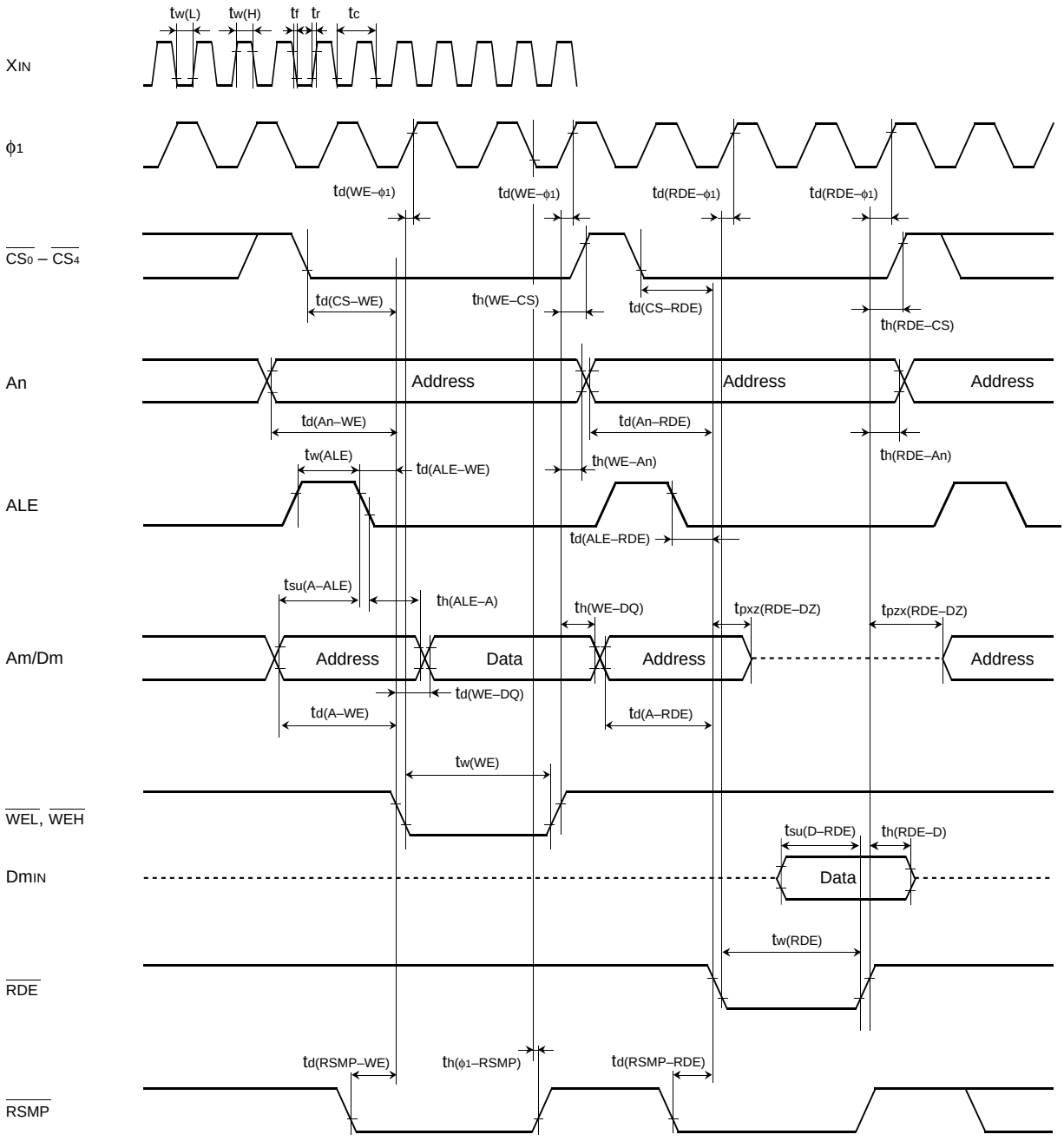
Memory expansion mode and microprocessor mode
(Wait 1 : The external area is accessed when wait bit = “0” and wait selection bit = “1”.)



Test conditions
- Vcc = 5 V ± 10%
- Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V
- Data input Dm_{IN} : V_{IL} = 0.8 V, V_{IH} = 2.5 V

[External bus mode B]

Memory expansion mode and microprocessor mode
(Wait 0 : The external memory area is accessed when wait bit = “0” and wait selection bit = “1”.)



Test conditions
- Vcc = 5 V ± 10%
- Output timing voltage : V_{OL} = 0.8 V, V_{OH} = 2.0 V
- Data input Dm_{IN} : V_{IL} = 0.8 V, V_{IH} = 2.5 V

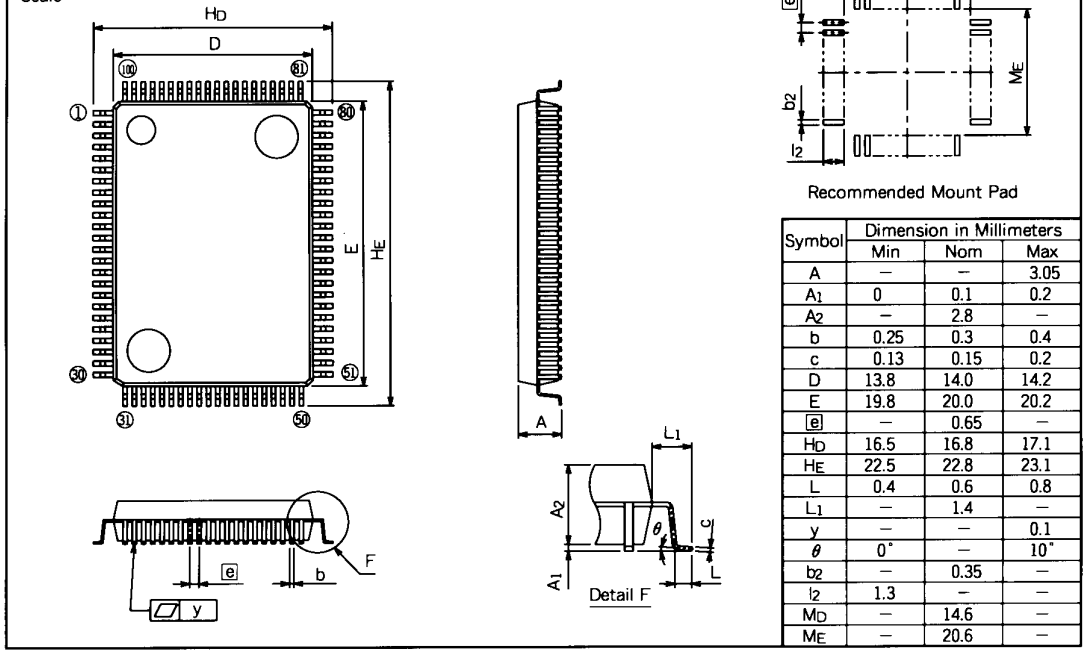
PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

PACKAGE OUTLINE

100P6S−A — Plastic 100pin 14×20mm body QFP

EIAJ Package Code	JEDEC Code	Weight(g)	Lead Material
QFP100-P-1420-0.65	—	1.58	Alloy 42

Scale :



Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	3.05
A_1	0	0.1	0.2
A_2	—	2.8	—
b	0.25	0.3	0.4
c	0.13	0.15	0.2
D	13.8	14.0	14.2
E	19.8	20.0	20.2
e	—	0.65	—
H_D	16.5	16.8	17.1
H_E	22.5	22.8	23.1
L	0.4	0.6	0.8
L_1	—	1.4	—
y	—	—	0.1
θ	0°	—	10°
b_2	—	0.35	—
l_2	1.3	—	—
M_D	—	14.6	—
M_E	—	20.6	—

PRELIMINARY

Notice: This is not a final specification.
Some parametric limits are subject to change.

MITSUBISHI MICROCOMPUTERS

M37736M4BXXXGP

SINGLE-CHIP 16-BIT CMOS MICROCOMPUTER

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